

- Seamless, Automatic Transition Between Two Input **Power Sources**
- Wide Input Voltage Range: 2.4V to 42V
- **E** Wide Output Voltage Range: 0.818V to V_{IN}
- ⁿ **Up to 2.5A Continuous Output Current**
- \blacksquare Pin-Selectable Priority and Ideal Diode-OR Modes
- Burst Mode[®] Operation, I_O = 2µA
- 95% Efficiency at 1A, V_{IN} = 12V, V_{OIII} = 5V
- 1µA Current in Shutdown
- Programmable Input UVLO Thresholds
- Input Valid, Priority Channel and PGOOD Indicators
- 200kHz to 2.2MHz Fixed Frequency PWM
- Synchronizable to an External Clock
- Current Mode Control with 60ns Minimum On-Time
- Minimal External Components
- Thermally Enhanced 28-Lead 4mm \times 5mm QFN and 28-Lead TSSOP Packages

Applications

- Portable Industrial/Communications Test Equipment
- Battery and Supercapacitor Backup Power
- Automotive Power with Battery Backup
-

FEATURES DESCRIPTION 42V, 2.5A Synchronous Step-Down Regulator with No-Loss Input PowerPath

The LTC[®]3126 is a high efficiency synchronous buck converterwithaninternalno-lossPowerPath™ supporting seamless operation from two separate input power sources. Pin-selectable ideal diode-OR and priority input modes with user programmable undervoltage lockout thresholds provide full control over the transition between the input power sources. The fast, automatic switchover provided by the internal PowerPath eliminates the need for hold-up capacitors and minimizes disturbances on the output rail. An active input channel indicator and independent input and output power good signals provide complete feedback of the power system status.

A wide 2.4V to 42V input voltage range, 2.5A output current capability and 2µA Burst Mode operation quiescent current facilitate use of the LTC3126 with a wide variety of power sources including supercapacitors, automotive batteries, unregulated wall adapters and single to multicell stacks of most battery chemistries. Additional features include 1µA current in shutdown, internal softstart and thermal protection. The LTC3126 is available in thermally enhanced 28-lead 4mm \times 5mm QFN and 28-lead TSSOP packages.

Uninterruptible Power Supplies Letter Linear Linear Technology, the Linear logo and Burst Mode are registered trademarks and PowerPath is a trademark of Linear Technology Corporation. All other trademarks are the property of their respective owners.

Typical Application

2MHz, 3.3V/2.5A Supply from Automotive and Battery Inputs

3126f

1

2

Absolute Maximum Ratings **(Note 1)**

Pin Configuration

ORDER INFORMATION <http://www.linear.com/product/LTC3126#orderinfo>

Consult LTC Marketing for parts specified with wider operating temperature ranges. *The temperature grade is identified by a label on the shipping container. For more information on lead free part marking, go to:<http://www.linear.com/leadfree/>

For more information on tape and reel specifications, go to: <http://www.linear.com/tapeandreel/>. Some packages are available in 500 unit reels through designated sales channels with #TRMPBF suffix.

ELECTRICAL CHARACTERISTICS The \bullet denotes the specifications which apply over the specified operating

junction temperature range, otherwise specifications are at T_A = 25°C (Note 2). PV_{IN1} = V_{IN1} = 24V, PV_{IN2} = V_{IN2} = 12V, **VSET1 = VSET2 = GND, unless otherwise noted.**

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Note 1: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

Note 2: The LTC3126 is tested under pulsed load conditions such that $T_J \approx T_A$. The LTC3126E is guaranteed to meet specifications from 0°C to 85°C junction temperature. Specification over the –40°C to 125°C operating junction temperature range are assured by design, characterization and correlation with statistical process controls. The LTC3126I specifications are guaranteed over the –40°C to 125°C operating junction temperature range. The LTC3126H specifications are guaranteed over the –40°C to 150°C operating junction temperature range. The LTC3126MP specifications are guaranteed and tested over the –55°C to

150°C operating junction temperature range. High temperatures degrade operating lifetimes; operating lifetime is derated for junction temperatures greater than 125°C.

Note 3: Current measurements are performed when the LTC3126 is not switching. The current limit values measured in operation will be somewhat higher due to the propagation delay of the comparators. **Note 4:** This IC includes overtemperature protection that is intended to protect the device during momentary overload conditions. The maximum rated junction temperature will be exceeded when this protection is active. Continuous operation above the specified absolute maximum operating junction temperature may impair device reliability or permanently damage the device.

Efficiency, $V_{OUT} = 3.3V$ **,**

 V_{IN} = 12V V_{IN} = 24V

 $\left| \begin{array}{c} \end{array} \right|$ L = 10µH

 $V_{IN} = 12V$ V_{IN} = 24V

MODE

3126 G05

┱

 $f_{SW} = 700K$ Hz

85

90

95

100

 $T_A = 25^\circ \text{C}$, unless otherwise noted.

Efficiency, $V_{OUT} = 1.8V$ **,** $f_{SW} = 2MHz$

Efficiency, V_{OUT} = 5V, $f_{SW} = 2MHz$ 100 90 80 70 Burst Mode EFFICIENCY (%) EFFICIENCY (%) 60 **OPERATION** 50 PWM 40 MODE **TITULI** 30 $L = 2.2 \mu H$ 20 , , , , , , , , , , , $V_{IN} = 12V$ 10 $V_{1N} = 24V$ Ω 0.0001 0.001 0.01 0.1 1 4

LOAD CURRENT (A)

3126 G07

Efficiency, $V_{\text{OUT}} = 3.3V$ **,**

LOAD CURRENT (A) 0.0001 0.001 0.01 0.1 1 4

THITEAR

3126f

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TA = 25°C, unless otherwise noted.

EXTV_{CC} Current vs Switching
Frequency 16 18 $V_{IN} = 12V$ V_{IN} = 24V

20 f_{SW} = 700kHz ${\sf f}_{\mathsf{SW}}$ = 2MHz 16 EXTV_{CC} CURRENT (mA) EXY_{CC} CURRENT (mA) 12 8 4 $LOAD = 1A$ $V_{OUT} = 5V$ 0 5 15 25 35 45 INPUT VOLTAGE (V) 3126 G14

EXTV_{CC} Current vs Input Voltage **Load Regulation**

V_{CC} LDO Voltage Drop vs
Switching Frequency

LINEAR

 $T_A = 25^\circ \text{C}$, unless otherwise noted.

Switching Frequency vs R_T

Reverse Current Out of the Unused Input (V_{IN1} or V_{IN2})

Minimum On-Time vs Temperature 56 60

Switching Frequency vs Temperature

Power Switch Resistance vs Temperature

High Side Current Limit Threshold vs Temperature

Temperature Rise vs Load Current

3126f

7

TA = 25°C, unless otherwise noted.

Minimum Load for Full Frequency Switching (No Pulse Skipping) 40 $f_{SW} = 700kHz$ $L = 4.7 \mu H$ V OUT = 5V 30 PWM/SYNC = HIGH LOAD CURRENT (mA) LOAD CURRENT (mA) 20 10 Ω 5 10 15 20 25 30 35 40 45

INPUT VOLTAGE (V)

3126 G30

Switching Waveforms, PWM Mode

Burst Mode Operation Threshold

VREF vs Temperature

Switching Waveforms,

Burst Mode Operation Load Step, 0.5A to 1.5A

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TA = 25°C, unless otherwise noted.

Hot Plug of Automotive Input, V_{IN1}

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PIN FUNCTIONS **(QFN/TSSOP)**

V_{CC}, PV_{CC} (Pins 2, 3/Pins 5, 6): Internal Linear Regulator Output and Power Supply for the Low Voltage Control Circuitry in the IC. Internal linear regulators generate a regulated voltage on these pins from either V_{IM1} , V_{IN2} or EXTV_{CC} . V_{CC} and PV_{CC} must be connected together in the application. A 4.7μF or larger bypass capacitor must be connected between these pins and ground. The V_{CC} rail remains powered in shutdown and can be used to supply up to 1mA to external loads.

EXTV_{CC} (Pin 4/Pin 7): V_{CC} Regulator Bootstrapping Pin. If this pin is forced to 3.15V or greater then $EXTV_{CC}$ will be used to power the internal V_{CC} rail. Typically, the EXTV_{CC} input is connected to the buck converter output voltage. Bootstrapping the internal V_{CC} rail in this fashion provides a significant efficiency advantage and reduced quiescent current especially in applications with high input voltage and low output voltage. If the EXTV_{CC} pin is left open then the V_{CC} rail will be powered from the V_{IN1} and V_{IN2} pins.

V_{SET1}, V_{SET2} (Pins 5, 6/Pins 8, 9): Programming Pins for the UVLO Thresholds on V_{IN1} and V_{IN2} . The voltage on the V_{SET1} and V_{SET2} pins programs the UVLO threshold for the power source inputs V_{IN1} and V_{IN2} , respectively. A voltage between zero and 1V programs a corresponding UVLO threshold between zero and 20V. However, there is also a fixed internal UVLO threshold (typically 2.34V) on each input which is always in effect. The voltage on $V_{\rm SFT1}$, can be set using a resistor divider from the accurate reference output, V_{REF} . Grounding $V_{SET 1,2}$ will allow the respective input $V_{\text{IN1,2}}$ to be used down to the fixed, internal UVLO threshold.

VREF (Pin 7/Pin 10): Voltage Reference Output for Powering Resistor Dividers to Set the $V_{\rm SET1}$ and $V_{\rm SET2}$ Inputs. The voltage at this pin is regulated by the IC to maintain a high precision, temperature stable 1.0V output. Resistive dividers from the V_{REF} pin can be used to set the voltage at the V_{SFT1} and V_{SFT2} pins and thereby program the UVLO threshold for each input. The V_{REF} output may also be used as a general purpose voltage reference in the application, providing a temperature stable reference for comparators, DACs or other functions. The total current drawn from this pin must be limited to 1mA and the total capacitive load should be limited to 470pF. If this pin is not used in the application (i.e., if there is no resistor from V_{RFF} to ground) then the V_{RFF} pin must be connected to V_{CC}.

GND (Pin 8/ Pin 11): Signal Ground. This pin is the ground connection for the control circuitry of the IC and must be tied to ground.

FB (Pin 9/Pin 12): Feedback Voltage Input. A resistor divider connected to this pin establishes the output voltage of the buck converter. Care should be taken in the routing of connections to this pin in order to minimize stray coupling to the SW, BST1, BST2, COM1 and COM2 pins.

RT (Pin 10/Pin 13): Switching Frequency Programming Pin. A resistor placed from this pin to ground sets the switching frequency of the buck converter.

PGOOD (Pin 11/Pin 14): Open-Drain Power Good Indicator for the Buck Converter Output Voltage. This output is driven low if the buck converter output voltage is more than 8.7% below the regulation voltage or more than 9.8% above the regulation voltage. The PGOOD pin is also driven low whenever the buck converter is disabled. The maximum voltage that can be applied to the PGOOD pin is 5.5V.

PRIORITY (Pin 12/Pin 15): Open-Drain Output Indicating That the Priority Input (V_{IN1}) Is Being Utilized. The PRIORITY pin is driven low if the part is enabled and the buck converter is operating from the priority input, V_{IM1} . In disable (ENA low) the PRIORITY pull-down is disabled, allowing the pin to float. The maximum voltage that can be applied to the PRIORITY pin is 5.5V.

PV_{IN2} (Pin 13/Pin 16): Secondary Power Source Input for the Buck Converter. In priority mode (DIODE pin low) the buck converter will only operate from this input if the priority input power source is under voltage. This pin must be bypassed with a 4.7µF or larger ceramic capacitor to ground. If the PV_{IN2} input will be subjected to inductive shorts to ground, then a power Schottky diode must be added from ground to PV_{IN2} to prevent this pin from being driven below ground.

ENA (Pin 14/Pin 17): Enable Input. Forcing the ENA pin low disables the input voltage comparators, the V_{REF} pin driver and the buck converter. The V_{CC} rail remains powered in disable and therefore ENA can be connected to V_{CC} to

PIN FUNCTIONS **(QFN/TSSOP)**

continuously enable the part. The maximum voltage that can be applied to the ENA pin is 5.5V.

PGND (Pins 18, 19, Exposed Pad Pin 29/Pins 21, 22, Exposed Pad Pin 29): Power Ground Connections. These pins must be connected to ground in the application.

For optimal thermal performance, the backpad should be soldered to the PC board and the PC board should be designed with the maximum possible number of vias connecting the backpad to the ground plane.

SW (Pins 17, 20/Pins 20, 23): Power Switch Inductor Connections. This pin should be connected to one side of the buck converter inductor.

COM1, COM2 (Pins 16, 21/Pins 19, 24): Negative Termination for Charge Pump Capacitors. External 0.1µF capacitors (with 5V rating or greater) must be connected between BST1 and COM1 and between BST2 and COM2.

BST1, BST2 (Pins 15, 22/Pins 18, 25): High Side Gate Driver Supply Rails. External 0.1µF capacitors (with 5V rating or greater) must be connected between BST1 and COM1 and between BST2 and COM2. These pins are used to generate a gate drive rail for the high side power devices.

DIODE (Pin 23/Pin 26): Logic Input Used to Select Between Ideal Diode-OR and Priority Modes. The integrated power path allows operation from either of two input power sources, V_{IN1} or V_{IN2} . An input is considered valid for use only if its voltage is above the UVLO threshold for that input as programmed by the respective voltage at the V_{SFT1} or V_{SFT2} pin. If DIODE is high then the part operates in ideal-diode mode and the buck converter will operate from the highest voltage valid input (V_{IN1} or V_{IN2}). If DIODE is low then the part operates in priority mode and the buck converter will operate from V_{IN1} whenever it is valid and will switch to V_{IN2} only if V_{IN1} becomes invalid. In either mode, if both inputs are under voltage then the buck converter will be disabled.

PV_{IN1} (Pin 24/Pin 27): Priority Power Source Input for the Buck Converter. In priority mode (DIODE pin low) the buck converter will preferentially operate from this input if both input power sources are valid (above their respective UVLO thresholds). This pin must be bypassed with a 4.7 μ F or larger ceramic capacitor to ground. If the PV_{IN1} input will be subjected to inductive shorts to ground, then a power Schottky diode must be added from ground to PV_{IN1} to prevent this pin from being driven below ground.

V_{IN1} (Pin 25/Pin 28): Priority Power Source Kelvin Connection. This pin must be bypassed with a 0.1µF ceramic capacitor to ground. The V_{IN1} pin must be connected to PV_{IM1} in the application.

VIN2 (Pin 26/ Pin 1): Secondary Power Source Kelvin Connection. This pin must be bypassed with a 0.1µF ceramic capacitor to ground. The V_{1N2} pin must be connected to PV_{IN2} in the application.

PWM/SYNC (Pin 27/Pin 2): PWM/Burst Mode Operation Control and External Synchronization Clock Input. Forcing this pin high causes the buck converter to operate in PWM mode. In PWM mode, the converter maintains fixed frequency operation over the widest range of load currents possible, leaving fixed frequency operation only at extremely light loads where the converter skips pulses to maintain regulation. Forcing the PWM/SYNC pin low causes the IC to utilize Burst Mode operation at light loads and automatically transition to PWM mode at higher load current. Burst Mode operation improves light load efficiency and significantly reduces no-load input quiescent current atthe expenseofmodestly increasedoutput voltage ripple. In addition, an external clock can be applied to the PWM/ SYNC pin for synchronization purposes. When synchronized to an external clock the buck converter operates in PWM mode (Burst Mode operation is disabled).

VALID1, VALID2 (Pins 1, 28/Pins 3, 4): Open-Drain Outputs Indicating Whether the V_{IN1} and V_{IN2} Inputs Are Valid. When the part is enabled (ENA is high) VALID1 and $\overline{VALID2}$ are driven low if the voltage at the V_{IN1} or V_{IN2} input is above the UVLO threshold set by the respective V_{SET1} or V_{SET2} pin. When the part is disabled (ENA is low) the VALID1 and VALID2 pull-downs are disabled allowing the pins to float. The maximum voltage that can be applied to the VALID1 and VALID2 pins is 5.5V.

BLOCK DIAGRAM Pin numbers shown for QFN package

Quick Reference

This section of the data sheet contains all of the equations necessary for external component selection as well as key part usage notes all compiled into one location for ease of use.

Switching Frequency

The buck converter switching frequency, f_{SW} , is set by the value of R_T resistor connected between the RT pin and ground according to the following equation:

$$
R_T = \frac{33.2 \text{MHz}}{f_{SW}} \text{ k}\Omega
$$

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Table 1. R_T Value for Common Switching Frequencies

Quick Reference

Output Voltage

The buck converter output voltage is set via a resistor divider connected to the FB pin as shown in Figure 1.

In most applications, choosing R_{TOP} equal to 1M Ω represents a good trade-off between quiescent current and robustness against PCB leakage. R_{BOT} can be determined by the following equation where V_{OUT} is the desired output voltage:

Figure 1. FB Resistor Divider

Inductor Value

If the buck converter will be operated at duty cycles greater than 50% (i.e., V_{IN} < 2 V_{OUT}) then the inductor value must be equal or greater than L_{MIN} as defined by the following equation:

$$
L_{MIN} = \frac{MHz}{f_{SW}} \cdot \frac{V_{OUT}}{2V} \mu H
$$

The peak-to-peak inductor ripple, ΔI_L , is given by the following equation.

$$
\Delta I_L = \frac{V_{OUT}}{f_{SW} \bullet L} \left(1 - \frac{V_{OUT}}{V_{IN}} \right)
$$

Output Capacitor

The recommended minimum output capacitor, C_{MIN} , is given below as a function of output voltage:

$$
C_{MIN} = \frac{1V}{V_{OUT}} 150 \mu F
$$

Table 3. Minimum Output Capacitor vs VOUT

Quick Reference

VIN1, VIN2 UVLO Thresholds

The V_{IN1} and V_{IN2} UVLO thresholds are set by the voltage on the V_{SFT1} and V_{SFT2} pins respectively. Each UVLO threshold can be set from a maximum of 20V down to the internal fixed UVLO threshold of 2.34V using a resistor divider from the V_{REF} output as shown in Figure 2. The rising UVLO threshold is given by the following equation:

$$
V_{UVLO1,2} = 20 V_{SET1,2} = 20 V \frac{R2}{R1 + R2}
$$

Grounding the $V_{\rm SET 1.2}$ pin will define the respective input as valid down to the fixed internal UVLO threshold of 2.34V.

Figure 2. Input UVLO Threshold Divider

External Synchronization Clock Frequency

The buck converter can be synchronized to an external clock applied to the PWM/SYNC pin. The frequency of the external clock must be higher than the internal oscillator frequency as set by the RT pin. In order to accommodate the $\pm 10\%$ possible variation in the oscillator frequency, the R_T resistor should be chosen to set the internal oscillator frequency at least 10% below the lowest synchronization frequency. For example, to synchronize to an external 1MHz clock, R_T should be picked to set the internal oscillator at 900kHz or lower.

Feedforward Capacitor

The feedforward capacitor, C_{FF} , as shown in Figure 1 improves the noise robustness of the FB pin and adds a zero to the loop at the frequency $f_{\rm ZFRO}$ given below:

$$
f_{\text{ZERO}} = \frac{1}{2\pi \cdot R_{\text{TOP}} \cdot C_{\text{FF}}}
$$

In most applications performance will be optimized if the zero frequency is set at approximately 16kHz. In applications with large output capacitance, a larger feedforward capacitor can be utilized to reduce the zero frequency and improve the transient response and phase margin. As shown in Figure 1, a 10k feedforward resistor, R_{FF} , can be added to improve noise immunity in applications with high output voltage ripple or a long distance between the resistor divider and V_{OUT} .

Open-Drain Outputs

The open-drain outputs (PGOOD, PRIORITY, VALID1 and VALID2) are low voltage pins and cannot be pulled up to a voltage higher than 5.5V. PGOOD is forced low in disable.

Logic Inputs

The logic input pins (DIODE, ENA, PWM/SYNC) are low voltage pins and cannot be forced above 5.5V. To force any of these pins continuously high, the pin can be connected to V_{CC} .

Important Usage Notes

- 1. PV_{IN1} and V_{IN1} must be connected together in the application. PV_{1N2} and V_{1N2} must be connected together in the application. PV_{IM1} and PV_{IN2} must each have a 4.7µF or larger bypass capacitor installed and placed as close to the pin as possible. In addition, V_{1N1} and V_{IN2} should have a separate 0.1µF bypass capacitor installed as close to the pin as possible.
- 2. The two SW pins must be connected together in the application.
- 3. V_{CC} and PV_{CC} must be connected together in the application and should be bypassed with a 4.7µF or larger capacitor.
- 4. If the V_{REF} pin is not used in the application (i.e., there is no resistor from V_{REF} to GND) then the V_{REF} pin must be connected to V_{CC} .
- 5. If PV_{IN1} or PV_{IN2} can be driven below ground in the application, for example due to large inductive ringing at the input, then Schottky diodes must be installed from ground to PV_{IN1}/PV_{IN2} to protect the LTC3126.

OPERATION

The LTC3126 is a dual-input synchronous monolithic buck converter featuring the ability to operate from two different input power sources with voltage ranges from 2.4V to 40V. An integrated lossless power path eliminates the need for an external diode-OR circuit or another type of external power path enabling a complete multi-input power supply solution with higher efficiency, fewer components, lower quiescent current and reduced drop-out voltage. The LTC3126 integrates all of the control circuitry required to automatically transition between two input power sources based on user programmable UVLO thresholds and selectable ideal-diode and priority modes. These features allow the LTC3126 to serve as a complete single chip power supply solution from a variety of different power sources including automotive, wall adapter, USB/Firewire and a wide range of battery chemistries. In addition, the LTC3126 is ideally suited for capacitor backup supplies with its ability to automatically transition to a capacitive backup rail when primary power is interrupted. A low 1µA quiescent current in disable and 2µA operating current make the LTC3126 ideally suited for battery powered and automotive applications.

PowerPath Operation

The power path controls whether the buck converter operates from the V_{IN1} or V_{IN2} input based on programmable undervoltage lockout thresholds for each input. The UVLO architecture used by the LTC3126 eliminates the need to connect external resistor dividers directly to the input voltages thereby providing a substantial reduction in quiescent current.

The $V_{\rm SFT1}$ and $V_{\rm SFT2}$ pins are used to set the undervoltage lockout thresholds for the two power source inputs V_{IN1} and V_{IN2} respectively. The UVLO threshold for each input can be independently set to any voltage from 20V down to the internal fixed UVLO threshold of 2.34V using an external resistor divider as shown in Figure 3. The V_{RFF} pin is regulated to a fixed, temperature stable 1.0V. An external resistor divider from the V_{REF} pin is used to establish the voltage at the V_{SET1} and V_{SET2} pins. The programmed voltage at the $V_{\text{SET1,2}}$ pin is compared to the respective input voltage (V_{IN1} or V_{IN2}) scaled down through an internal resistor divider with a ratio of 20:1 to determine ifthatinputisundervoltage. As a result, a voltage

Figure 3. Programming the UVLO Thresholds on V_{IN1} and V_{IN2}

range of zero to 1V on the $V_{SET1.2}$ corresponds to a UVLO threshold of zero to 20V on $V_{1N1,2}$. In addition, there is a fixed internal minimum UVLO threshold of 2.34V which is always enforced independent of the programmed voltage on the V_{SET1} and V_{SET2} pins. To enable a channel down to this minimum UVLO threshold, the respective $V_{\text{SFT1,2}}$ pin can be simply connected to ground.

The LTC3126 power path has two operational modes as determined by the state of the DIODE logic input. With DIODEhigh, thepartutilizes idealdiode-ORmode andoperates from the input that has the higher voltage (assuming both inputs are above their respective UVLO thresholds). If one input is in UVLO then the other input will be utilized. If both inputs are in UVLO then the buck converter will be disabled. With the DIODE input low, the part operates in priority mode whereby V_{IN1} is always given priority and is utilized as long as it is above its UVLO threshold. If V_{IN1} is in UVLO then V_{IN2} is utilized as long as it is not in UVLO. If both V_{1N1} and V_{1N2} are in UVLO then the buck converter is disabled.

All current drawn from the V $_{REF}$ pin is supplied by one of the inputs, V_{IN1} or V_{IN2} . If neither input is above its respective UVLO threshold, then this current will be drawn from the input with the higher voltage. Otherwise, this current will be drawn by the active channel as determined by the power path. The V_{RFF} pin current will be supplied by the $EXTV_{\text{CC}}$ pin if that pin is utilized and has a valid voltage present.

3126f The PRIORITY, VALID1 and VALID2 open-drain outputs provide feedback on the state of the power path. The VALID1 and VALID2 outputs indicate that the respective input is present and above its UVLO threshold. Specifically,

OPERATION

the VALID1 pin is driven low if the part is enabled (ENA is high) and V_{IN1} is above its UVLO threshold. The VALID2 pin is driven low if the part is enabled and V_{1N2} is above its UVLO threshold. The PRIORITY pin is driven low if the part is enabled and the buck converter is operating from the priority channel, V_{IM1} . The PRIORITY pin provides the ability to determine which input is being utilized in idealdiode mode when both inputs are valid.

The V_{CC} rail stays powered even when the LTC3126 is disabled (ENA is low) as long as either V_{IN1} or V_{IN2} is powered. In this disabled state, the V_{CC} output is powered from whichever input (V_{IN1} or V_{IN2}) is higher in voltage independent of the state of the DIODE pin. Given that the V_{CC} output remains powered in shutdown, the ENA pin can be connected to V_{CC} to continuously enable the part.

Buck Converter Operation

The LTC3126 buck converter utilizes constant frequency switching with peak current mode control to provide low noise operation. The switching frequency can be set from 200kHz to 2.2MHz by appropriate choice of the RT pin resistor. In addition, the buck converter can be synchronized to an external clock applied to the PWM/SYNC pin.

The buck converter always operates from a single input power source (V_{IN1} or V_{IN2}) at any time. The input that is used is determined by the state of the DIODE input, the programmed UVLO thresholds and the voltage of each input as described in the PowerPath Operation section. Each switching cycle begins with the high side switch of the active input turning on. The high side switch remains on until the inductor current reaches the current level set by the output of the internally compensated error amplifier. At that point, the low side synchronous rectifier turns on and remains on for the remainder of the cycle or until the inductor current falls to zero. The error amplifier continuously adjusts the commanded current level to maintain regulation of the FB pin voltage.

If PWM/SYNC is forced high or has an external clock applied, then the buck converter will operate in PWM mode. In PWM mode operation, the buck converter will maintain fixed frequency switching at all possible load currents, switching to pulse skipping only at very light load currents when the minimum on-time of the SW is reached. PWM mode provides low noise, fixed frequency operation and low output voltage ripple over the widest possible range of load currents and should be used when it is necessary to maintain the lowest possible noise levels. With PWM/ SYNC forced low, the converter will automatically transition to Burst Mode operation at light loads to increase efficiency and reduce no-load quiescent current.

The LTC3126 buck converter is current limit protected to prevent damage to the IC during output overload and short-circuit conditions. If the inductor current exceeds the high side switch current limit threshold then the high side switch is turned off for the remainder of the cycle. If the inductor current exceeds the low side current limit threshold, then the high side switch will remain off during the next cycle to prevent increasing the inductor current further during the high side switch minimum on-time. In addition, the switching frequency is reduced by a factor of 16 if the FB voltage is below 200mV to ensure control of the inductor current is maintained during output overcurrent conditions.

The internal circuitry of the buck converter including the gate drivers is powered from V_{CC} . Internal LDOs generate the V_{CC} rail from the active input, V_{IN1} or V_{IN2} . In applications where the buck converter output is 3.3V or greater, the V_{CC} rail can be bootstrapped by connecting the EXTV_{CC} pin to the buck converter output. This allows a third LDO to generate the V_{CC} rail directly from EXTV_{CC}. Given that the buck converter has much greater efficiency than the LDOs, bootstrapping via the $EXTV_{CC}$ pin increases the efficiency of the converter and reduces its quiescent current. This is particularly the case for applications with high input voltage, low output voltage and high switching frequencies.

Input UVLO Thresholds on V_{IN1}, V_{IN2}

The undervoltage lockout threshold for each input, V_{IN1} and V_{1N2} , is set by the voltage on the V_{SET} and V_{SET} pins respectively. A voltage between OV and 1V on V_{SFT1} , linearly programs a corresponding UVLO threshold of zero to 20V. There is also an additional internal minimum undervoltage lockout threshold of 2.34V on each input which is always in effect independent of the voltage at the V_{SFT1} , pins. To allow an input to operate fully down to the internal minimum UVLO threshold, the respective V_{SFT1} , pin can be connected to ground.

In most applications, the voltage at the V_{SET1} and V_{SET2} pin is established using a resistor divider from the V_{RFF} pin as shown in Figure 4. The corresponding rising UVLO threshold is given by the following equation:

$$
V_{UVLO1,2} = 20 V_{SET1,2} = 20 V \frac{R2}{R1 + R2}
$$

When neither input is valid (above its respective UVLO threshold), the current drawn from the V_{REF} pin will add directly to the quiescent current of the higher voltage input $(V_{IN1}$ or $V_{IN2})$. Therefore, use of large value resistors in the $V_{\text{SFT1,2}}$ divider string will reduce the quiescent current. However, larger value resistors also result in lower immunity to noise and leakage currents. A reasonable compromise in most applications is to utilize a total resistor string impedance of 1MΩ.

Figure 4. Setting the Input UVLO Thresholds

To minimize quiescent current and eliminate an external resistor it is also possible to set both UVLO thresholds via a single resistor string as shown in Figure 5. The upper resistor divider tap is connected to whichever pin, V_{SFT1} or V_{SFT2} , requires the higher UVLO threshold.

Figure 5. Setting Both Input UVLO Thresholds Using a Single Resistor String

Resistor R3 can be chosen independently and selecting R3 equal to 200k is a reasonable starting choice for most applications. The value of R2 and R1 can then be determined from the following equations where V_{UV} o_H is the undervoltage lockout threshold on the higher voltage channel and V_{HIVO} is the UVLO threshold on the lower voltage channel:

$$
R2 = R3 \left(\frac{V_{UVLOH}}{V_{UVLOL}} - 1 \right)
$$

$$
R1 = (R2 + R3) \left(\frac{20}{V_{UVLOH}} - 1 \right)
$$

If the resulting total resistance through the resistor chain $(R1 + R2 + R3)$ is larger or smaller then desired, the choice of R3 can be adjusted in the appropriate direction and the calculation for R2 and R1 can be repeated.

Input Hold-Up Capacitance

The LTC3126 features internal micropower UVLO comparators which minimize the quiescent current required by the application. However, due to their low operating current, the UVLO comparators exhibit a significant delay when responding to an undervoltage condition. Sufficient input hold-up capacitance must be provided to ensure the voltage on the utilized channel remains sufficient to power the buck converter until the transition to the secondary channel is completed.

Consider the example illustrated in Figure 6 where the LTC3126 is being powered by the priority input (V_{IN1}) at 12.8V and the UVLO threshold on the V_{IN1} channel is

programmed to 10V. At time t_1 , the priority input is unplugged and the buck converter begins discharging the input capacitor. At time t_2 , the UVLO threshold is reached but the buck converter remains operating from the priority channel due to the comparator delay. At time t_3 , after comparator delay t_{DELAY} , the buck converter switches over to the secondary input (V_{IN2}) and the input capacitor on V_{IN1} maintains its voltage since there is no longer any current being drawn on that channel. In this example, the input capacitor on V_{IN1} must be large enough that V_{IN1} remains at sufficient voltage to maintain the output voltage in regulation until time t_3 . If V_{IN1} is allowed to drop lower than the regulated output voltage then the buck converter output will temporarily lose regulation during the transition.

Figure 6. Waveforms During Transition from V_{IN1} to V_{IN2}

The required value of hold-up capacitance, C_{IN} , can be estimated from the following equation where V_{OUT} is the buck converter regulated output voltage, I_{LOAD} is the buck converter load current, η is the buck converter efficiency, V_{UVLO} is the falling UVLO threshold of the active channel and V_{MIN} is the minimum required input voltage needed for the buck converter to maintain regulation.

$$
C_{IN} = \frac{2V_{OUT} \cdot I_{LOAD} \cdot t_{DELAY}}{\eta \left(V_{UVLO}^2 - V_{MIN}^2\right)}
$$

In the example from Figure 6, the UVLO threshold, V_{UVLO} , is 10V. The typical comparator delay of $t_{\text{DFI AY}} = 60 \mu s$ is specified in the Electrical Characteristics section of this data sheet. For the sake of this example, consider a buck converter output voltage of 3.3V with a 2.5A load. The buck converter dropout voltage at 2.5A is approximately 700mV. Therefore, the minimum buck converter input voltage, V_{MIN} , required to maintain regulation is 3.3V + 700mV = 4V. Finally, assuming an efficiency of 80%, the minimum required input hold-up capacitance on the priority channel can be calculated as:

$$
C_{IN} = \frac{2(3.3V)(2.5A)(60\mu s)}{0.80[(10V)^{2} - (4V)^{2}]}
$$

= 14.7 $\frac{\mu s \cdot A}{V}$ = 14.7 μF

Therefore, in this example a minimum capacitor value of 15 μ F or greater must be utilized on V_{IN1} to maintain regulation of the buck converter output throughout the transition to the secondary channel. In practice, an additional guardband should be included to account for variations in component tolerances and delays.

Soft-Start

The LTC3126 incorporates an internal soft-start circuitwith a nominal duration of 7.5ms. The soft-start is implemented by a linearly increasing ramp of the error amplifier reference voltage during the soft-start duration. As a result, the duration of the soft-start period is largely unaffected by the size of the output capacitor or the output regulation voltage. Given the closed-loop nature of the soft-start implementation, the converter is able to respond to load transients that occur during the soft-start interval. The soft-start period is reset by thermal shutdown, when the buck converter is disabled via the ENA pin and when both inputs are in UVLO.

VREF Output

The V_{RFF} output is a regulated, temperature stable 1.00V voltage reference. It is intended primarily to be used to establish the V_{SET1} and V_{SET2} pin voltages. However, it can also be used for other functions as long as the total current drawn from the pin is limited to 1mA or less. In addition to that restriction, there is also a maximum amount of capacitance that can be placed on the V_{RFF} pin in order to maintain suitable phase margin in the internal pin driver. The maximum recommended capacitance on the V_{RFF} pin is 470pF or less. If the V_{RFF} pin is not being used in the application (i.e., there is no resistor from V_{BFF} to GND) then the V_{REF} pin should be connected to V_{CC}. The V_{RFF} pin cannot be left floating. The V_{RFF} pin is only powered when the part is enabled (ENA is high).

Buck Converter Switching Frequency

TheLTC3126buck converterutilizes fixed-frequencyPWM to achieve low output ripple and low noise operation. The switching frequency can be set from 200kHz to 2.2MHz by appropriate selection of the R_T resistor placed between the RT pin and ground. See the Quick Reference section for details on selecting the value for R_T .

Higher switching frequencies facilitate the use of smaller inductors as well as smaller input and output capacitors which results in a smaller solution size and reduced componentheight. However, higher switchingfrequencies also generally reduce conversion efficiency due to increased switching losses.

The on-time of the buck converter SW pin decreases as the step-down ratio from V_{IN} to V_{OIII} increases and as the switching frequency is increased. The minimum switch on-time, $t_{ON(MIN)}$, is the smallest duration on-time that the SW pin can generate. If the required on-time is shorter than the minimum on-time then the part will pulse skip to maintain regulation. Although regulation of the output will be maintained, pulse skipping results in lower frequency switching and increased output voltage ripple. In order to avoid pulse-skipping operation, the switching frequency should be selected to be less than $f_{SW(MAX)}$ as given by the following equation where $t_{ON(MIN)}$ is the minimum SW pin on time with a typical value of 60ns:

$$
f_{SW(MAX)} = \frac{V_{OUT}}{V_{IN} \cdot t_{ON(MIN)}}
$$

The SW minimum on-time is a function of load current and temperature as shown in the Typical Performance Characteristics section.

Input Capacitors

To ensure proper functioning of the buck converter, minimize EMI and reduce input ripple, the PV_{IM1} and PV_{IN2} pins must each be connected to a low ESR bypass capacitor with a value of at least 4.7µF. Ceramic capacitors with X5R or X7R dielectric are recommended. Each bypass capacitor must be located as close as possible to the respective pin and should connect to the ground plane via the shortest route possible.

When powered through an inductive connection such as a long cable, the inductance of the power source and the input bypass capacitor form a High-Q resonant LC filter. In such applications, hot-plugging into a powered source can lead to a significant voltage overshoot, even up to twice the nominal input source voltage. Care must be taken in such situations to ensure that the absolute maximum input voltage rating of the LTC3126 is not violated. See Linear Technology Application Note 88 for solutions to increase damping in the input filter and minimize this voltage overshoot.

The V_{IN1} and V_{IN2} pins provide power to the V_{CC} regulator and other internal circuitry. Each of these pins should be connected to a 0.1µF bypass capacitor located as close to the pin as possible.

Buck Output Capacitor

A low ESR capacitor should be utilized at the output of the buck converter in order to minimize output voltage ripple. For most applications, a ceramic capacitor with X5R or X7R dielectric is the optimal choice. There is also a minimum required output capacitor value as specified in the Quick Reference section. The crossover frequency of the voltage control loop increases with lower output capacitance and therefore a minimum capacitance value is required to limit the bandwidth and ensure stability of the voltage feedback loop. Given that the loop gain is dependent on the voltage divider ratio, the minimum required output capacitor is a function of the output voltage as well. At lower output voltages, the loop gain is higher and a larger output capacitor is required to maintain a fixed loop crossover frequency. The larger recommended output capacitance at low output voltages also helps to reduce the magnitude of voltage steps on load transients in proportion to the reduced output voltage rail in order to maintain a constant percentage deviation.

Increasing the value of the buck converter output capacitor will decrease the bandwidth of the feedback loop. If the output capacitor gets too large, the crossover frequency may decrease too far below the compensation zero leading to degraded phase margin and underdamped transient response. In such cases, the phase margin and transient performance can be improved by increasing the size

of the feedforward capacitor in parallel with the upper resistor divider resistor to restore the full bandwidth of the feedback loop.

Feedforward Resistor

In applications where there is a long connection between the feedback resistor divider and the point at which the output voltage is sensed, it is recommended that a 10k feedforward resistor (R_{FF}) be added in series with the feedforward capacitor as shown in Figure 7 below. The feedforward resistor prevents high frequency noise on the V_{OUT} trace from coupling into the sensitive FB node. The addition of a 10k feedforward resistor will have little impact on the frequency response of the control loop since the divider pole location is dominated by the values of resistors R_{TOP} and R_{ROT} .

Figure 7. Feedforward Resistor (R_{FF}) for Improved **Noise Robustness**

Inductor Selection

The choice of inductor value influences both the efficiency and the magnitude of the output voltage ripple. Larger inductance values will reduce inductor current ripple and will therefore lead to lower output voltage ripple. For a fixed DC resistance, a larger value inductor will yield higher efficiency via reduced RMS and core losses. However, a larger inductor within a given inductor family will generally have a greater series resistance, thereby counteracting this efficiency advantage. The peak-to-peak current ripple, ∆I_L, given by the following equation will be largest at the highest input voltage experienced in the application.

$$
\Delta I_L = \frac{V_{OUT}}{f_{SW} \cdot L} \left(1 - \frac{V_{OUT}}{V_{IN}} \right)
$$

A reasonable choice for ripple current is $\Delta I_L = 1A$ which represents 33% of the minimum current limit. The DC current rating of the inductor should be at least equal to the maximum load current plus half the ripple current in order to prevent core saturation and loss of efficiency during operation. To optimize efficiency the inductor should have a low DC resistance. As a general guideline, the inductor resistance (ESR) should be approximately equal to the low side switch resistance (70mΩ) or less.

High values of inductor ripple current will reduce the output current capability of the converter since higher ripple increases the peak switch current and will therefore trip the current limit at a lighter load current. The maximum output current is equal to the current limit minus half the peak-to-peak ripple current as shown in the following equation where I_{LIMIT} is the threshold of the high side switch current limit:

$$
I_{\text{OUT}(MAX)} = I_{\text{LIMIT}} - \frac{\Delta I_{\text{L}}}{2}
$$

In addition, there is a minimum inductor value required to maintain stability of the current loop as determined by the fixed internal slope compensation. Specifically, if the buck converter is going to be utilized at duty cycles over 50%, the inductance value must be at least equal to L_{MIN} as given by the following equation:

$$
L_{MIN} = \frac{MHz}{f_{SW}} \cdot \frac{V_{OUT}}{2V} \mu H
$$

To ensure sufficient slope compensation if the external synchronization feature is being used, the inductor must be sized for the lowest possible switching frequency the part will experience which is determined by the internal oscillator frequency.

PGOOD Output

The open-drain PGOOD output is driven low whenever FB is more than +9.8%/–8.7% (typical) from the FB reference voltage. The PGOOD output is also driven low whenever the buck converter is disabled. The maximum voltage that can be applied to the PGOOD output is 5.5V. The PGOOD comparator has a deglitching delay of approximately 200 μ s.

V_{CC} Regulators and Bootstrapping with EXTV_{CC}

The V_{CC} rail powers the internal control circuitry and power device gate drivers of the LTC3126. Two internal low dropout linear regulators provide the ability to generate this rail from either V_{IN1} or V_{IN2} . When the IC is disabled (ENA low) the V_{CC} rail is powered by the higher voltage input, V_{IN1} or V_{IN2} , regardless of the state of the V_{SFT1} , V_{SET2} and DIODE pins. When the IC is enabled, the input voltage comparators on the V_{SFT1} and V_{SFT2} pins become active and the V_{CC} rail will be powered by the active channel. In ideal diode mode (DIODE high) the active channel is the valid input with the higher voltage. In priority mode (DIODE low) the active channel is V_{IN1} if V_{IN1} is valid or V_{1N2} otherwise (assuming it is valid). If both V_{1N1} and V_{1N2} are in UVLO then the higher voltage input will be utilized to power the V_{CC} rail.

A third linear regulator allows the V_{CC} rail to be powered via the $EXTV_{CC}$ pin which can be connected to the buck converter output or an auxiliary rail with a voltage above 3.15V. When operating at high input voltages, the losses in the V_{CC} regulator powered from the input voltage can become a significant factor in conversion efficiency and can even become a substantial source of power dissipation. A significant performance improvement can be obtained by connecting the $EXTV_{CC}$ input to the buck converter output so that the gate drive current is provided through the high efficiency buck converter rather than the less efficient linear regulator. This is of particular benefit at higher input voltages, lower output voltages and higher switching frequencies. The EXTV_{CC} pin is only utilized to power the V_{CC} rail when the buck converter is operating.

Thermal Considerations

The LTC3126 is designed to operate continuously up to its full rated 2.5A output current. However, when operating at high current levels there will be significant heat generated within the IC. In addition, in many applications the V_{CC} regulator is operated with large input-to-output voltage differential resulting in significant levels of power dissipation in its pass element which can add significantly to the total power dissipated within the IC. To ensure full output current capability and optimal efficiency, careful

consideration must be given to the thermal environment of the IC. This is even more important in applications that function over an extended ambient temperature range.

Specifically, the exposed die attach pad of both the QFN and TSSOP packages must be soldered to the PC board and the PC board should be designed to maximize the conduction of heat out of the IC package. This can be accomplished by utilizing multiple vias from the die attach pad connection to other PCB layers containing a large area of exposed copper.

If the die temperature exceeds approximately 170°C, the IC will enter overtemperature shutdown and all switching will be inhibited. The part will remain disabled until the die cools by approximately 10°C. The soft-start circuit is re-initialized in overtemperature shutdown to provide a smooth recovery when the fault condition is removed.

PCB Layout Guidelines

The LTC3126 buck converter switches large currents at high frequencies. Special attention must be paid to the PC board layout to ensure a stable, noise-free and efficient application circuit. Figures 6 and 7 show representative PC board layouts for each package option to outline some of the primary considerations. A few key guidelines are listed below.

- 1. The parasitic inductance and resistance of all circulating high current paths should be minimized. This can be accomplished by keeping the routes to the inductor, output capacitor and $PV_{IN1/2}$ bypass capacitors as short and as wide as possible. Capacitor ground connections should via down to the ground plane by way of the shortest route possible. The bypass capacitors on PV_{IN1} , PV_{IN2} and V_{CC} should be placed as close to the IC as possible and should have the shortest possible return paths to ground.
- 2. The exposed pad in both packages provides one of the primary paths for heat generated within the package. The IC must be soldered down to the backpad and the backpad area should be filled with vias connecting it to the ground plane.

- 3. There should be an uninterrupted ground plane under the entire converter in order to minimize the crosssectional area of the high frequency current loops. This minimizes EMI and reduces the inductive drops in these loops thereby minimizing SW pin overshoot and ringing.
- 4. Connections to the PV_{IM1} , PV_{IM2} and SW pins should be made as wide as possible to reduce the series impedance. This will improve efficiency and reduce the thermal resistance.
- 5. To prevent large circulating currents in the ground plane from disrupting operation of the part, all small-signal grounds should either return directly to the small-signal ground pin (GND) or via down to the ground plane close to the GND pin and not near the power stage components. This includes the ground connections for the R_T resistor, the FB resistor divider and the V_{SFT1} and V_{SFT2} resistor dividers.

Figure 8. Recommended PC Board Layout for QFN Package

- 6. Keep the routes connecting to the high impedance noise sensitive inputs (FB, RT, V_{SET1} , V_{SET2}) as short as possible to minimize noise pickup.
- 7. The BST1/BST2 pins transition at the switching frequency to the full input voltage. To minimize radiated noise and coupling, keep the routes connecting to the boost capacitors as short as possible and keep these routes away from all sensitive circuitry and pins (FB, RT, V_{SFT1}, V_{SFT2}).
- 8. The connection to the V_{IN1} pin (Pin 25) should be separate from the connection to the PV_{IN1} (Pin 24) and should have a separate 0.1µF bypass capacitor. This will prevent noise from the PV_{IN1} trace from being coupled into the sensitive V_{IN1} pin.

Figure 9. Recommended PC Board Layout for TSSOP Package

12V, 1MHz Step-Down Converter with Dual Inputs

12V, 2MHz Step-Down Converter with Dual Inputs

5V, 2MHz Step-Down Converter with Dual Inputs

0.1µF 0.1µF ╢ пr COM1 L1 BST2 COM2 BST1 6V TO 42V 3.3 µH VIN1 V_{OUT}
5V 4.7µF PV_{IN1} SW ᡓ $EXTV_{C}$ 2.5A C_{OUT}
22µF 6V TO 42V VIN2 ਵ 10pF \sum_{1} 4.7µF ×2 PV_{IN2} ᡓ FB PV_{CC} LTC3126 $\overline{}$ RT $\overline{}$ M $\overline{}$ \overline V_{CC}
ENA $\sum_{16.5k}$ 4.7µF VREF ᡓ PRIORITY VALID1 L1: TOKO FDSD0518
C_{OUT}: MURATA GRM43ER71A226KE01L V_{SET1} VALID2 V_{SET2}
PWM/SYNC PGOOD 91% EFFICIENCY, V_{IN} = 12V, 1A LOAD
87% EFFICIENCY, V_{IN} = 24V, 1.5A LOAD
3µA NO LOAD I_Q AT V_{IN} = 24V
390mV DROPOUT AT 1A LOAD
680mV DROPOUT AT 2A LOAD DIODE GND PGND 3126 TA06

0.1 uF 0.1 uF ╫ BST2 COM2 BST₁ COM1 L1 4.2V TO 42V 4.7µH VIN1 V_{OUT}
3.3V 4.7 μ F \Box PV_{IN1} SW EXTV_{CC} 2.5A Cout 4.2V TO 42V 47 u V_{IN2} ਵ 10pF \lessgtr 909k 4.7µF PV_{IN2} FB PV_{CC} LTC3126 $\begin{array}{ccc} \hline \text{RT} & \text{301k} \\ \hline 44.2k \end{array}$ V_{CC}
ENA 44.2k 4.7µF VREF **PRIORITY** L1: COILCRAFT XAL4030 V_{SET1} VALID1 VALID2 V_{SET2}
PWM/SYNC PGOOD 91% EFFICIENCY, V_{IN} = 12V, 1A LOAD
87% EFFICIENCY, V_{IN} = 24V, 1A LOAD
2µA NO LOAD I_Q AT V_{IN} = 24V
330mV DROPOUT AT 1A LOAD DIODE GND PGND Ŧ 끟 3126 TA07 660mV DROPOUT AT 2A LOAD

3.3V, 750kHz Step-Down Converter with Dual Inputs

3.3V, 2MHz Step-Down Converter with Dual Inputs 0.1µF 0.1µF

1.8V, 750kHz Step-Down Converter with Dual Inputs

1.8V, 2MHz Step-Down Converter with Dual Inputs

*The step-down converter can operate over the specified input voltage range without any pulse skipping for loads from 250mA to 2.5A. However, in all applications, the converter can operate from an input voltage as high as 42V, but pulse skipping may occur if operated above the specified voltage range. Pulse skipping is not detrimental to the IC, but can result in significant output voltage ripple and is therefore generally avoided while in nominal operating conditions.

Automotive and Photovoltaic Powered 5V USB Supply

Photovoltaic Panel Disconnect

5V, 2A Supply from Wall Adapter and Lead-Acid Backup Battery

INDUCTOR CURRENT 2A/DIV V_{OUT}
200mV/DIV VIN1, VIN2 5V/DIV

2A LOAD

3.3V/2.5A Supply from 24V Wall Adapter and Lead-Acid Battery

INDUCTOR CURRENT

2A/DIV

50µs/DIV

3126 TA13d

INDUCTOR CURRENT

2A/DIV

50µs/DIV

3126 TA13e

Package Description

Please refer to http://www.linear.com/product/LTC3126#packaging for the most recent package drawings.

5. EXPOSED PAD SHALL BE SOLDER PLATED

6. SHADED AREA IS ONLY A REFERENCE FOR PIN 1 LOCATION

ON THE TOP AND BOTTOM OF PACKAGE

Package Description

Please refer to<http://www.linear.com/product/LTC3126#packaging> for the most recent package drawings.

FE Package

2. DIMENSIONS ARE IN _{MILLIMETERS}

3. DRAWING NOT TO SCALE

(INCHES) *DIMENSIONS DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.150mm (.006") PER SIDE FOR EXPOSED PAD ATTACHMENT

